Controller

PS5012-E12C

Features	Specifications		
Host Interface	 PCIe Gen 3x4 (Bandwidth: 8GT/s x4) Compatible with PCIe Gen I(2.5Gbps), Gen II(5Gbps), Gen III(8Gbps) Compliance with PCI Express Base Specification Revision 3.1 Compliance with NVMe 1.3 		
Processor	Dual-CPU architecture with built-in 32-bit microcontrollerTSMC 28nm process technology		
Flash Controller	 Up to 4 Channels with 16 chips enable (CE) Flash transfer rate up to 667MT/s Capacity up to 2TB Support 3D TLC and QLC NAND flash memory Compliance with Toggle 3.0 and ONFi 4.0 Flash I/O operating voltage supply 1.2V/1.8V 		
DRAM Controller	DDR3L (16 bit, 1600Mbps)DDR4 (8/16 bit, 1600Mbps)		
Data Reliability	 Phison 3rd generation LDPC ECC & RAID ECC DDR ECC engine End-To-End Data Path Protection 		
Security	AES 256 encryption enginePyriteTCG OPAL 2.0		
Performance	 Sequential Read up to 2000MB/s Sequential Write up to 1600MB/s 4K Random Read up to 420K IOPS 4K Random Write up to 435K IOPS 		
Power Management	· L1.2 < 5mW		
Temperature Range	Operating range: 0~70°CStorage range: -40~85°C		
Package	• 324-ball TFBGA, 12 mm x 12 mm		
Peripheral	 Built-in internal thermal sensor GPIO pins Built-in UART function I2C and SPI for external ROM 		



Solutions

PS5012-E12C

Capacity ¹	128GB	256GB	512GB	
Interface	PCIe Gen3x4 NVMe 1.3			
Form Factor	M.2 2280-S2			
NAND Flash	3D TLC			
Performance (Up to) ^{2,3}				
Sequential Read	1800 MB/s	2000 MB/s	2000 MB/s	
Sequential Write	600 MB/s	1200 MB/s	1600 MB/s	
4K Random Read	105K MB/s	210K MB/s	390K MB/s	
4K Random Write	150K MB/s	330K MB/s	430K MB/s	
Power ⁴				
Supply Voltage	M.2 3.3V ± 5%			
Active Read (Average)	3.3W	3.5W	3.5W	
Active Write (Average)	2.3W	3.1W	3.5W	
PS3	16mW	16mW	18mW	
Low Power PS4 (L1.2)	2mW	2mW	2mW	
Temperature				
Operating ⁵	0°C - 70°C			
Non-Operating	-40°C - 85°C			
Advanced Features	End-to-End Data ProtectionPyrite/OPAL SupportThermal Monitoring			

¹ 1GB = 1,000,000,000 bytes



² 1MB/s = 1,000,000 bytes / second

 $^{^{\}rm 3}$ Performance is based on Crystal Disk Mark 6.0.0 for sequential test and IOmeter for random test

⁴ Measured power consumption during sequential read/write test on Crystal Disk Mark 6.0.0

 $^{^{\}rm 5}$ Operational temperature is measured by device temperature sensor